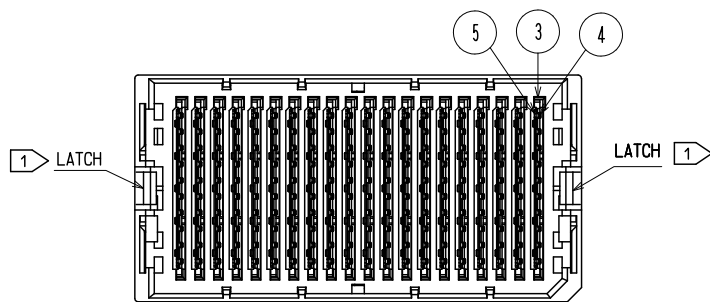
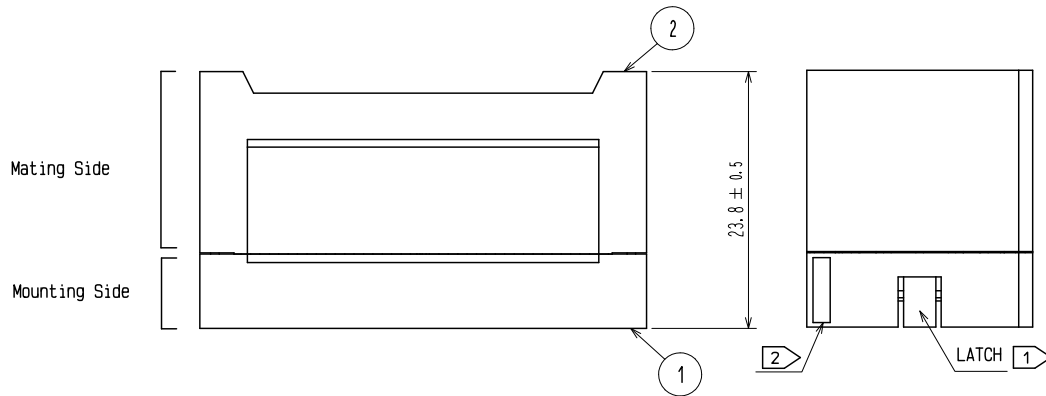
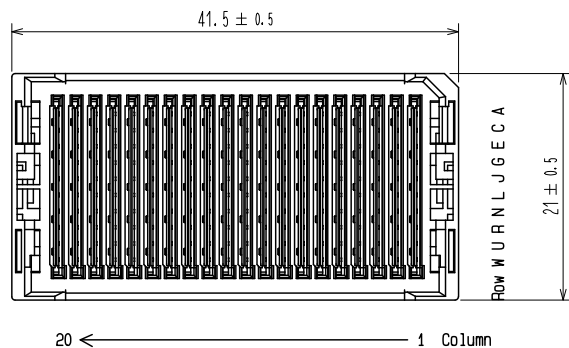
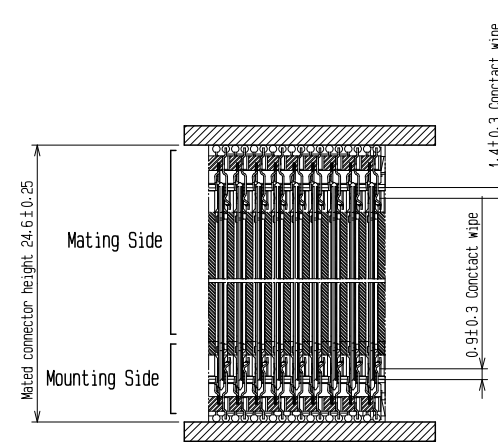


Fig. 1(FREE)



Mating Cross Section (Free)

- NOTE.
- 1 Mounting side is mated with the receptacle:IT3M-200S-BGA(**) and fixed with the latch.
 - 2 Lot No. shall be marked on the indicated position.
 - 3 The indicated mother board and daughter card shall be fastened to the additional reinforcements to prevent the stress on IT3*-200S-BGA(**) solder joints.
 4. More information of this product is available in HIROSE document :ETAD-F0347 "IT3 design guideline".
 5. This product consists of 200 signal lines and 180 ground lines.
 6. 40pcs of this products are packed in a soft tray.
 7. Standard package of 80pcs are packaged in a carton box.

3	PC	BLACK	UL94V-0						
2	PBT	GRAY	UL94V-0	5	Copper Alloy	CONTACT AREA:NICKEL(1.5μm)+GOLD (0.76μm)			
1	PBT	BLACK	UL94V-0	4	Copper Alloy	CONTACT AREA:NICKEL(1.5μm)+GOLD (0.76μm)			
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS		
UNITS	mm	SCALE	2 : 1	REV	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
				1		DIS-F-004000	TK.KIKUCHI	TM.MATSUO	09.07.17
		APPROVED	T. MATSUO	06/20/2008	DRAWING NO. EDC-157240-01				
		CHECKED	T. MATSUO	06/20/2008	PART NO. IT3-200P-25H(03)				
		DESIGNED	M. NAGATA	06/20/2008	CODE NO. CL636-0155-6-03				
		DRAWN	M. NAGATA	06/20/2008					